



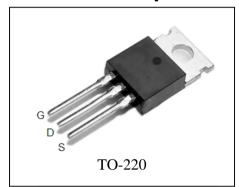
Features

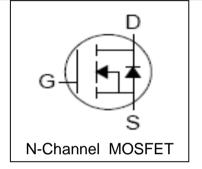
- 68V/88A, RDS (ON) = $6m\Omega$ (Typ.) @ VGS=10V
- Ultra Low On-Resistance
- Exceptional dv/dt capability
- Fast Switching and Fully Avalanche Rated
- 100% avalanche tested
- 175°C Operating Temperature
- Lead Free and Green Available

Applications

- Switching Application Systems
- Inverter Systems

Pin Description





Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit				
Common Ratin	gs (T _A =25°C Unless Otherwise Noted)						
V_{DSS}	Drain-Source Voltage						
V_{GSS}	Gate-Source Voltage		±25	V			
TJ	Maximum Junction Temperature		175	°C			
T _{STG}	Storage Temperature Range		-55 to 175	°C			
Is	Diode Continuous Forward Current	T _C =25°C	88 ^①	А			
Mounted on La	rge Heat Sink						
I _{DP}	300µs Pulse Drain Current Tested	T _C =25°C	320	Α			
I.	Continuous Proin Current()/ 10)()	T _C =25°C	88	۸			
I _D	Continuous Drain Current(V _{GS} =10V)	T _C =100°C	65	Α			
Б	Mariana Barra Biania dia a	T _C =25°C	120	14/			
P_D	Maximum Power Dissipation	T _C =100°C	60	W			
$R_{ heta JC}$	Thermal Resistance-Junction to Case	1.25	°C/W				
Drain-Source A	valanche Ratings						
E _{AS}	Avalanche Energy, Single Pulsed		225	mJ			



Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

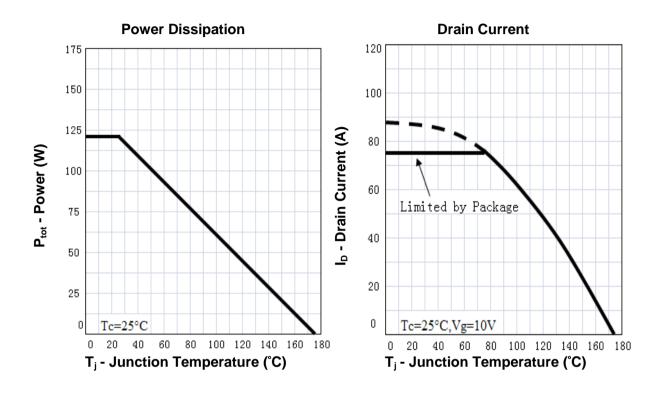
0	Downwater.	Took Condition	I	l lm!t			
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit	
Static Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	68			V	
	Zoro Coto Voltago Drain Current	V_{DS} = 68V, V_{GS} =0V			1		
I _{DSS}	Zero Gate Voltage Drain Current	T _J =85°C	;		30	μΑ	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250\mu A$	2	3	4	V	
I _{GSS}	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$			±100	nA	
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} = 10V, I _{DS} =40A		6	8	mΩ	
Diode Ch	aracteristics						
V _{SD}	Diode Forward Voltage	I _{SD} =40A, V _{GS} =0V			1.2	V	
trr	Reverse Recovery Time	Isp=40A, dlsp/dt=100A/μs		49		ns	
Qrr	Reverse Recovery Charge	-isb=40A, disb/dt=100A/μs		93		nC	
Dvnamic	© Characteristics						
R_G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz		1.4		Ω	
C _{iss}	Input Capacitance	Vgs=0V,		2900			
C _{oss}	Output Capacitance	V _{DS} =30V,		340		pF	
C_{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz		200			
t _{d(ON)}	Turn-on Delay Time			13			
t _r	Turn-on Rise Time	VDD=30V, RL=0.8 Ω ,		15		ns	
t _{d(OFF)}	Turn-off Delay Time	Ids=40A, Vgen= 10V, Rg=8Ω		29			
t _f	Turn-off Fall Time			55			
Gate Cha	rge Characteristics 5						
Q_g	Total Gate Charge			65			
Q_{gs}	Gate-Source Charge	Vps=54V, Vgs= 10V, lps=40A		12		nC	
Q_{gd}	Gate-Drain Charge	100-40/		21			

- Notes: ①Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
 - 2) Pulse width limited by safe operating area.

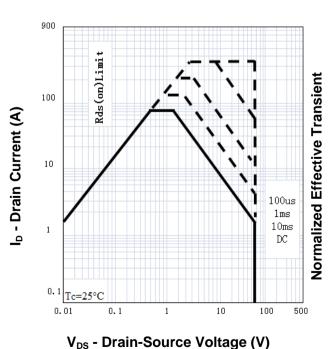
 - (4) Pulse test; Pulse width≤300µs, duty cycle≤2%.
 - ⑤Guaranteed by design, not subject to production testing.



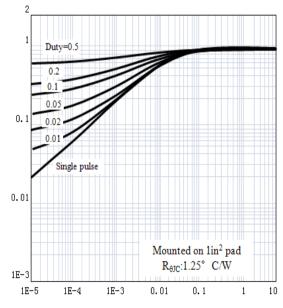
Typical Characteristics



Safe Operation Area



Thermal Transient Impedance

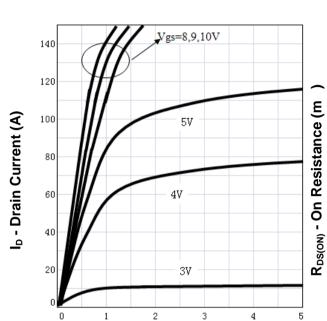


Square Wave Pulse Duration (sec)

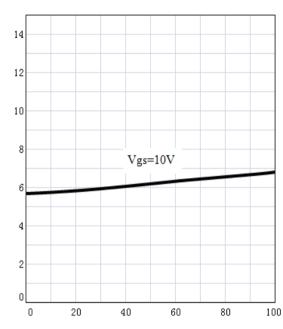


Typical Characteristics

Output Characteristics



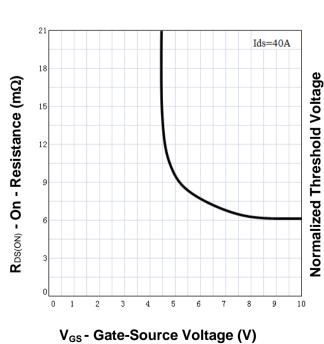
Drain-Source On Resistance



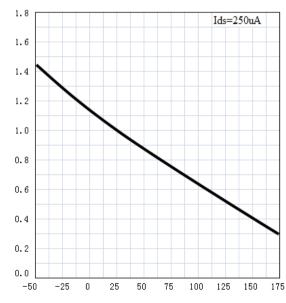
V_{DS} - Drain-Source Voltage (V)

I_D - Drain Current (A)

Drain-Source On Resistance



Gate Threshold Voltage

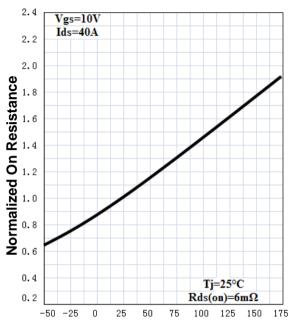


T_j - Junction Temperature (°C)



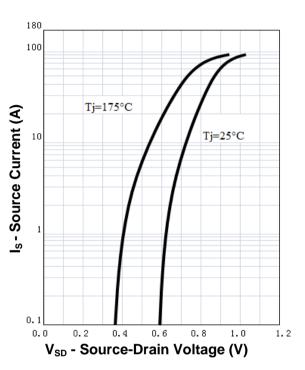
Typical Characteristics

Drain-Source On Resistance

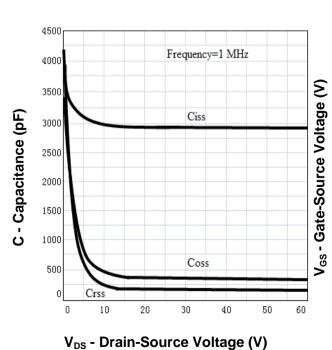


T_i - Junction Temperature (°C)

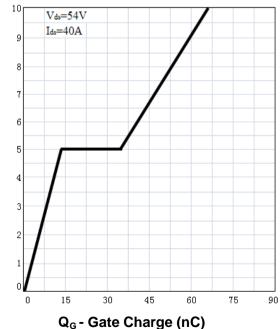
Source-Drain Diode Forward



Capacitance

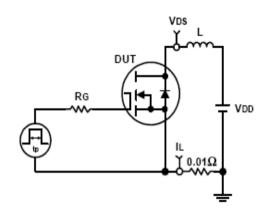


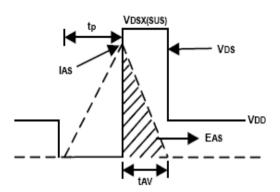
Gate Charge



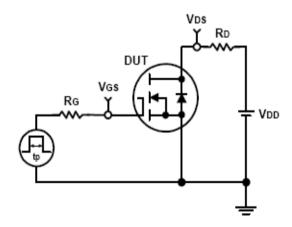


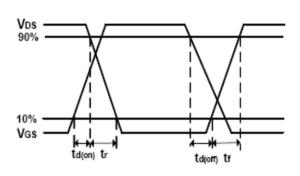
Avalanche Test Circuit and Waveforms





Switching Time Test Circuit and Waveforms







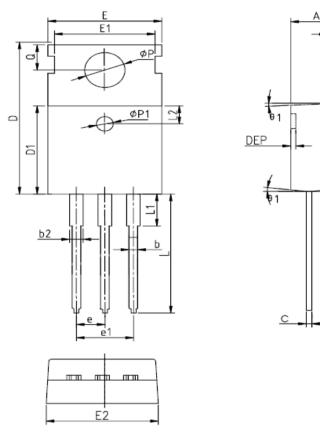
Ordering and Marking Information

Device	Marking	Package	Packaging	ing Quantity Reel Size		Tape width	
RU6888R	RU6888R	TO-220	Tube	50	-	-	



Package Information

TO-220FB-3L



		MM			INCH			MM		INCH			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.57	4.70	0.173	0.180	0.185	Øp1	1.40	1.50	1.60	0.055	0.059	0.063
A1	1.27	1.30	1.33	0.050	0.051	0.052	e	2.54BSC		0.1BSC			
A2	2.35	2.40	2.50	0.093	0.094	0.098	e1	5.08BSC		0.2BSC			
b	0.77	-	0.90	0.030	-	0.035	H1	6.40	6.50	6.60	0.252	0.256	0.260
b2	1.23	-	1.36	0.048	-	0.054	L	12.75	-	13.17	0.502	-	0.519
С	0.48	0.50	0.52	0.019	0.020	0.021	L1	-	-	3.95	-	-	0.156
D	15.40	15.60	15.80	0.606	0.614	0.622	L2	2.50REF.		0.098REF.			
D1	9.00	9.10	9.20	0.354	0.358	0.362	Øр	3.57	3.60	3.63	0.141	0.142	0.143
DEP	0.05	0.10	0.20	0.002	0.004	0.008	Q	2.73	2.80	2.87	0.107	0.110	0.113
Е	9.70	9.90	10.10	0.382	0.389	0.398	θ 1	5°	7°	9°	5°	7°	9°
E1	-	8.70	-	-	0.343	-	θ 2	1°	3°	5°	1°	3°	5°
E2	9.80	10.00	10.20	0.386	0.394	0.401							

ALL DIMENSIONS REFER TO JEDEC STANDARD DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS



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